

03-30-1999

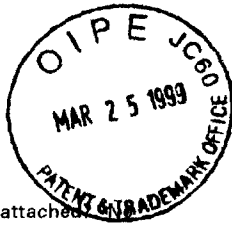


To the Assistant Commissioner for Patents: Please

100997387

or copy(ies) thereof.

1. Name of conveying party(ies):

Yoshikazu NAKATA
Takeshi KASAI

Additional name(s) of conveying party(ies) attached?

2. Name and address of receiving party(ies):

Name: SUMITOMO METAL (SMI) ELECTRONICS
DEVICES INC.

Internal Address:

Street Address: 2701-1, Aza-Iwakura, Higashibun,
Omine-cho, Mine-shi, Yamaguchi 759-2212, Japan

City: , State: ZIP:

3. Nature of conveyance:

☒ Assignment Merger
Security Agreement Change of Name
OtherExecution Date: March 7, 1999Additional name(s) & address(es) attached? No

4. Application number(s) or patent number(s):

(X) This document is being filed together with a new application, and the execution date of the application is: March 7, 1999

A. Patent Application No.

(09/250,282)

B. Patent No.

Additional numbers attached? No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: WENDEROTH, LIND & PONACK, L.L.P.

Internal Address: _____

Street Address: 2033 K Street, N.W., Suite 800City: Washington, State: DC ZIP: 200066. Total number of applications and patents involved: 17. Total fee (37 C.F.R. § 3.41). \$40.00

[99-0151*/WMC/1428]

Enclosed Check No. 32698

Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*Warren M. Cheek, Jr., Reg. No. 33,367

Name of Person Signing

Warren Cheek Jr.
SignatureMarch 25, 1999

Date

Total number of pages including cover sheet, attachments, and document: 3

Mail documents to be recorded with required cover sheet information to:

03/30/1999 BMGUYEN 00000100 09250282

FC:581

40.00 DP

Commissioner of Patents and Trademarks
Box Assignments
Washington, D.C. 20231

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

NAKATA Yoshikazu

KASAI Takeshi

Insert Name(s)
of Inventor(s)

the undersigned hereby sell(s) and assign(s) to

SUMITOMO METAL (SMI) ELECTRONICS DEVICES INC.

2701-1, Aza-Iwakura, Higashibun,
of Omine-cho, Mine-shi, Yamaguchi 759-2212 Japan

Insert Name(s)
of Assignee(s)

Address

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

CHIP PACKAGE AND METHOD FOR MANUFACTURING THE SAME

Title of
Invention

for which an application for patent in the United States has been executed by the undersigned on

March 7, 1999

Date of Signing
of Application

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, DC 20006, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date March 7, 1999, Name of Inventor Yoshikazu Nakada

Date March 7, 1999, Name of Inventor Takeshi Kasei

Date _____, Name of Inventor _____

Date _____, Name of Inventor _____

Date _____, Name of Inventor _____

Date _____, Name of Inventor _____

(This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.)

Witness Tetsuo Takano

Witness Yasichi Matuda

ACKNOWLEDGEMENT

_____ } ss

This _____ day of _____, 19_____, before me
personally came the above-named _____

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

SEAL

Official Signature

Official Title

The above application may be more particularly identified as follows:

U.S. Application Serial No. _____ Filing Date _____

Applicant Reference Number _____ Atty Docket No. _____

Title of Invention _____